

An abstract graphic on the left side of the image, composed of numerous thin, light green lines that curve and swirl together to form a complex, organic shape resembling a stylized flower or a dynamic energy field.

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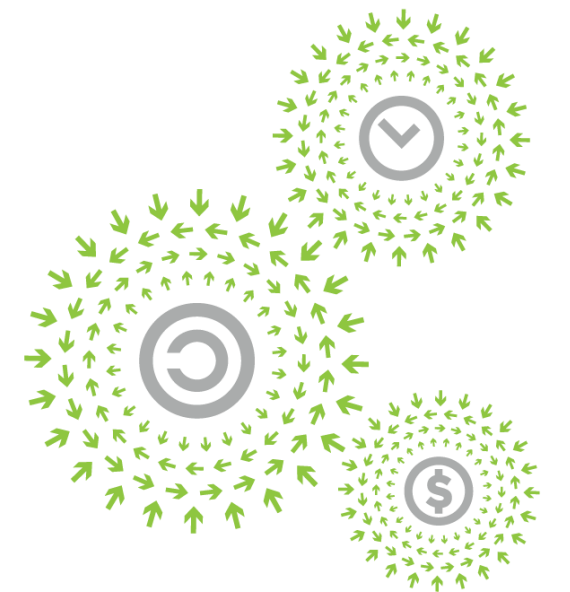


SERVER

Datacenter-ready Secure Control Module and Interface

for Modular Building Block Architecture (MBA, *The Catalyst*)

Siamak Tavallaei, Principal Architect
Microsoft, Azure



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Outline

- Motivation
- Approach
- Examples
- Requesting Participation and Feedback



SERVER



Specifications

TTM

- You have developed a production-ready server with a PCIe Slot.
- A solution provider has built a fully-compatible PCIe Add-in-Card with a unique feature.
- How long will it take you to integrate that PCIe AIC into your Server?

TTM

- You have developed a solution (e.g., a new server)
- Your CSP customer learns about it and likes it so much that wants to deploy it into the Datacenter in 3 months?
- How would you do that?

Modular Building Block Architecture (MBA)

- Small building blocks allow flexible and agile system integration to meet the needs of various use cases
- Clearly defined input/output ports for interoperability with CPU boards from various suppliers
- Connector/Cable-based IO Slots offer flexible choice of high-speed IO for AICs

DC-SCM Facilitates MBA

MBA is a Catalyst for interoperable *Innovation*!

A commonly designed secure control module for datacenters, **DC-SCM**, enables the design and deployment of CPU/Memory Complexes and Expansion Chassis based on guidelines from CPU and SoC suppliers to become simply a **routine exercise**!

Modular in every way!

“The conductor and the musician interpreting the composer’s work”
Vincent Van Gogh

Architectural Specification
Detailed Design
Product Manufacturing

Modular in every way!

“The conductor and the musician interpreting the composer’s work”
Vincent Van Gogh

Mechanical Design
Electrical Design
Software/Firmware Design
Security and Management
Debug

Examples of Modular Building Block Architecture

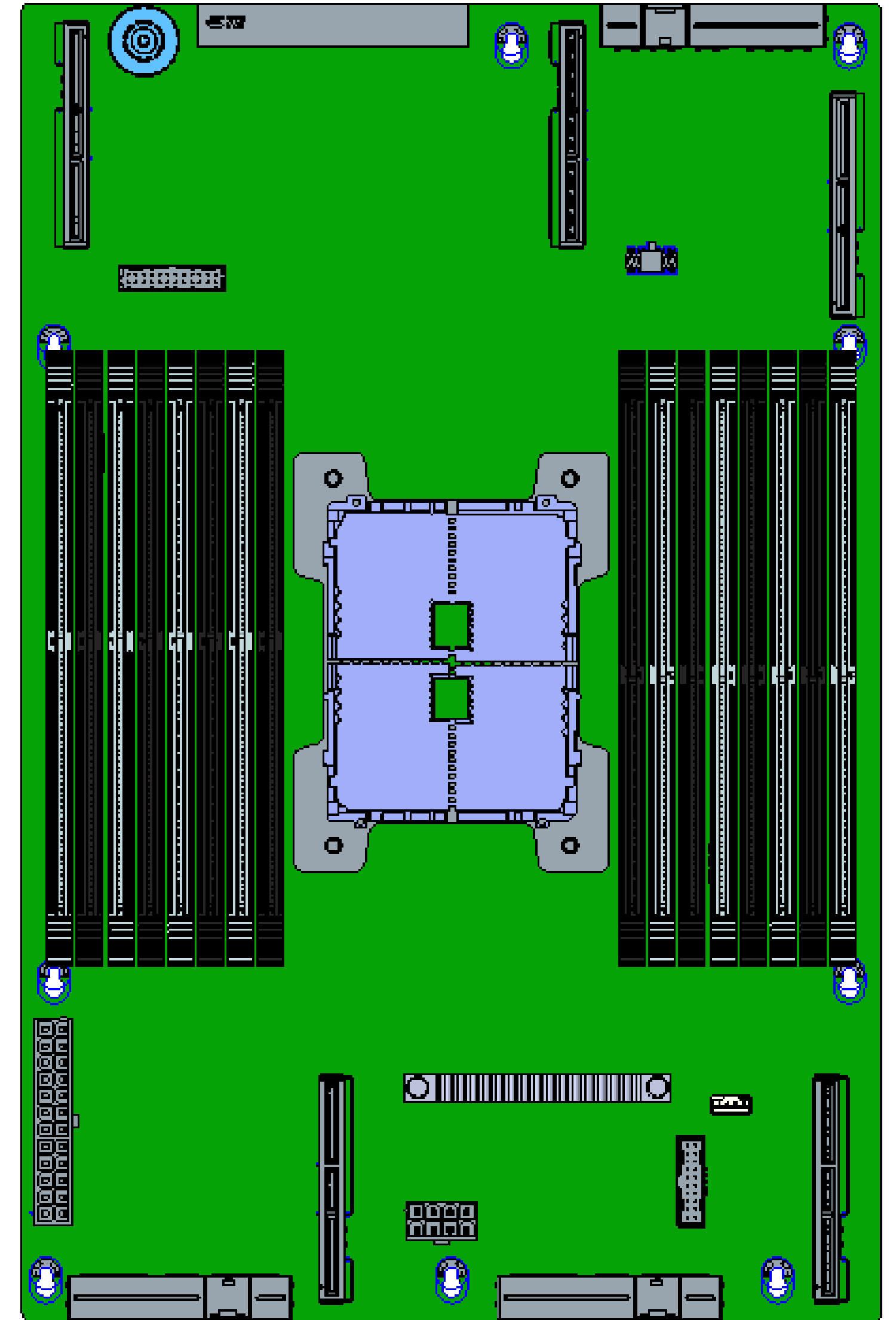
For a successful Modular Building Block Architecture, we need:

- Compute Modules (CPU/Memory/IO) (**CMIOM**)
- IO & Accelerator Add-in Card Modules (**AIC**)
- Security, Control, and Management (**SCM**)
- Data-plane Control
- An Interconnect



CPU/Mem/IO Module

Just the essential Central Compute Elements
And high-speed Memory and IO Connectors

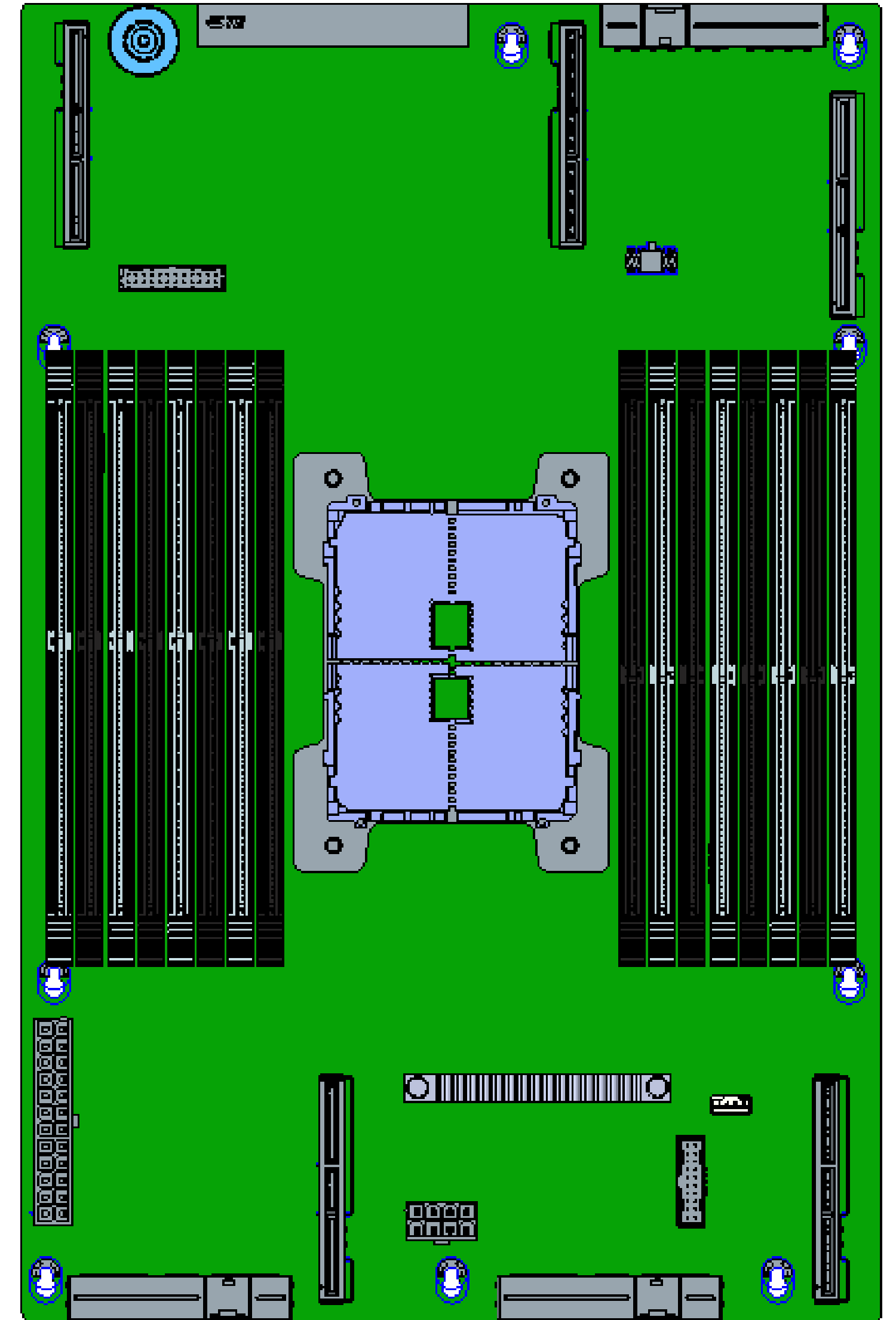


CPU/Mem/IO Module

Just the essential Central Compute Elements

And high-speed Memory and IO Connectors
Close to the SoC

Get ready for *PCIe Gen-5!*

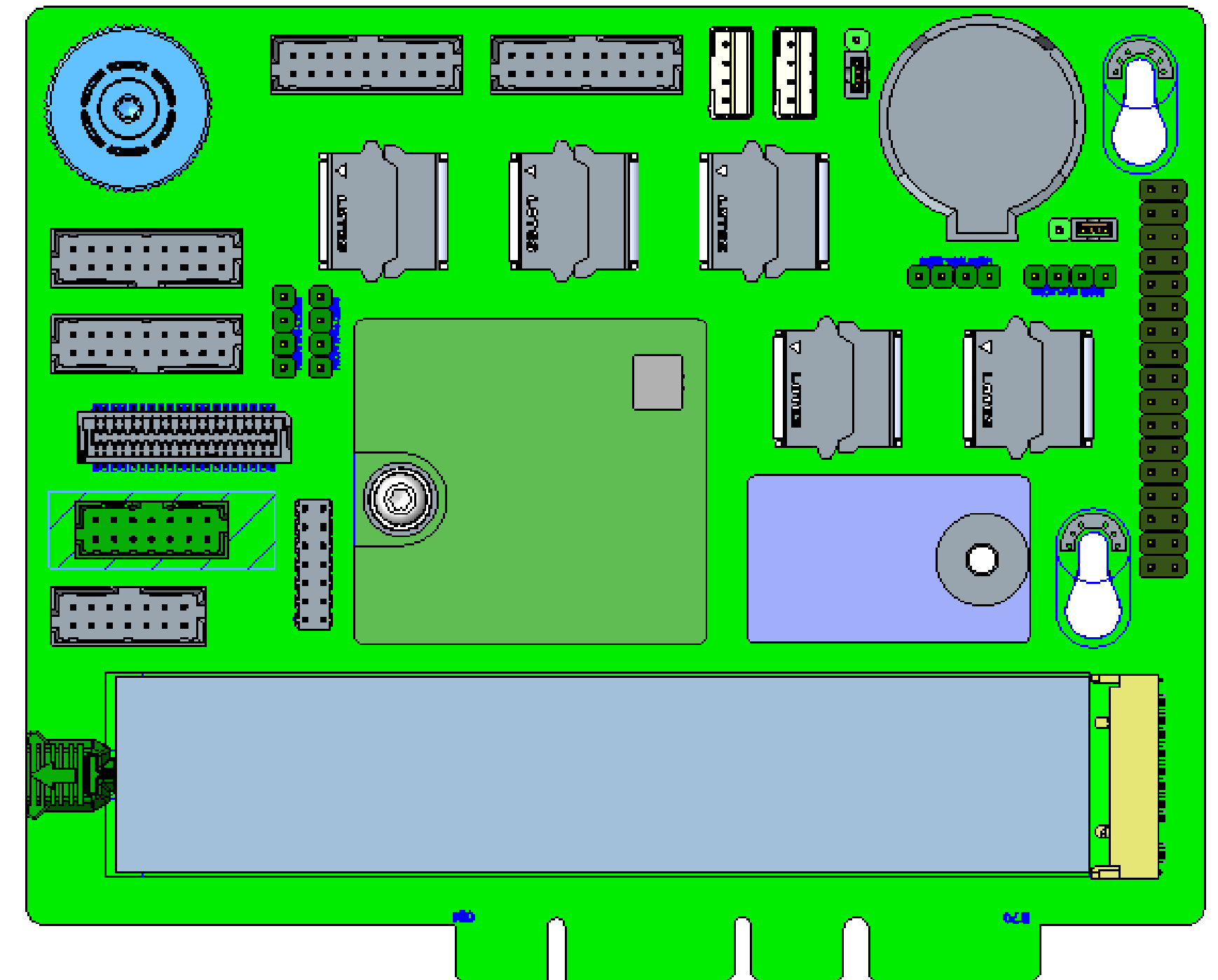


DC-SCM

Everything Else!

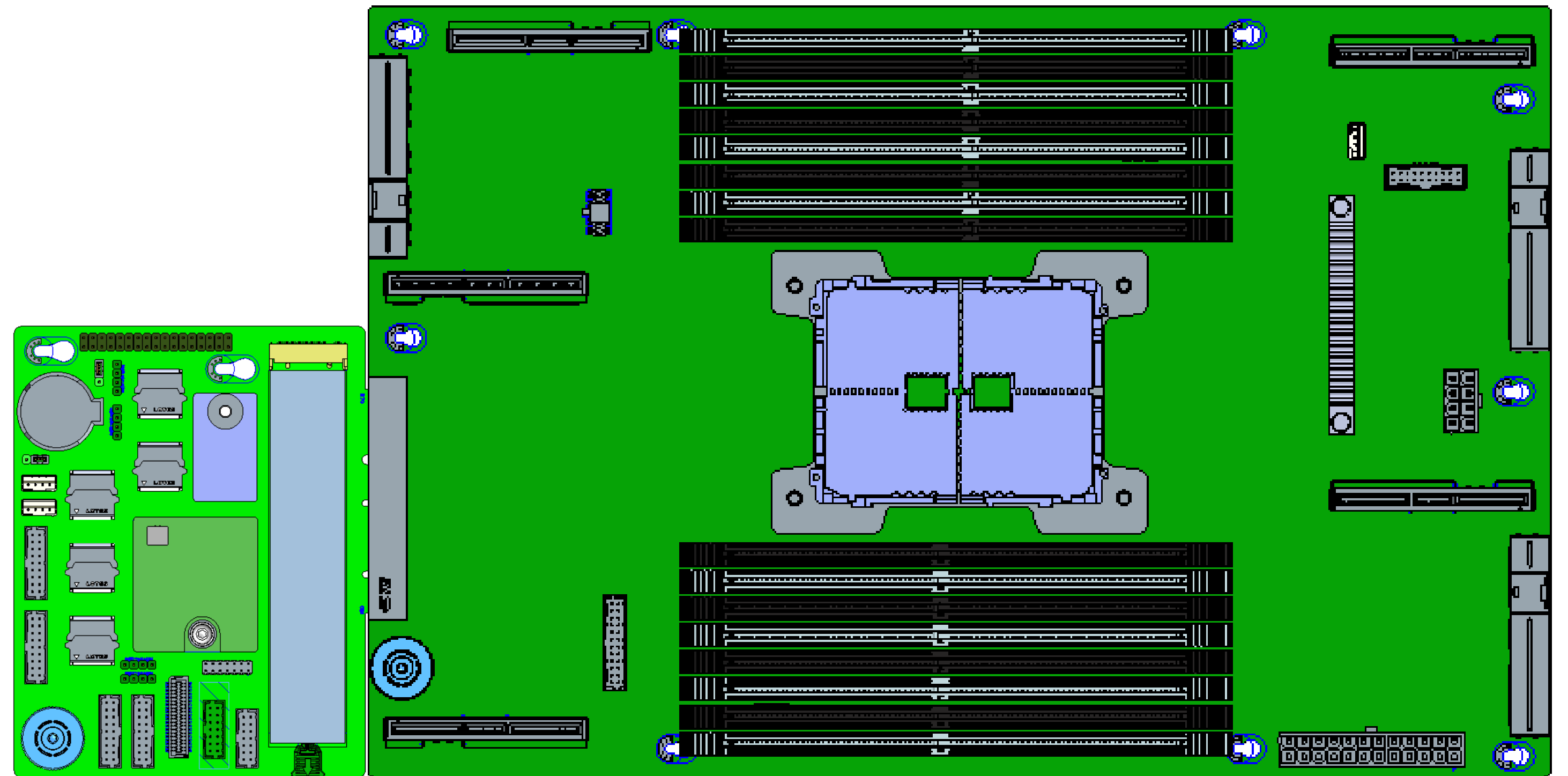
Security, Control, Management

DC-SCM

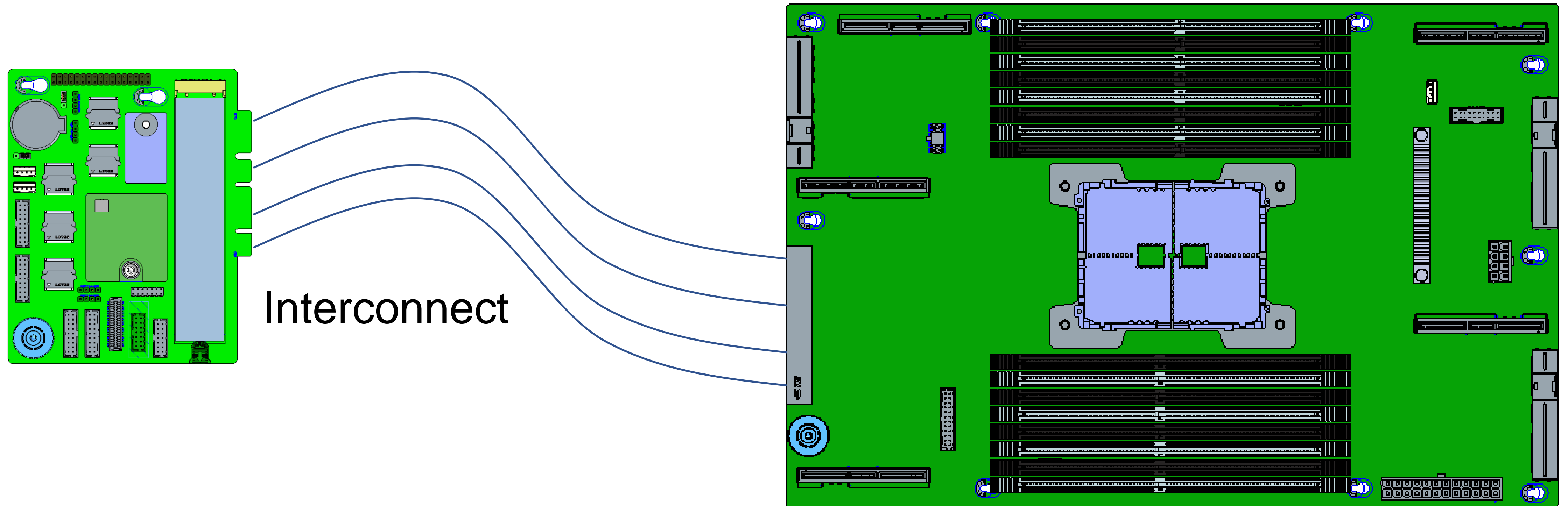


DC-SCI

DC-SCM + CPU/Mem/IO

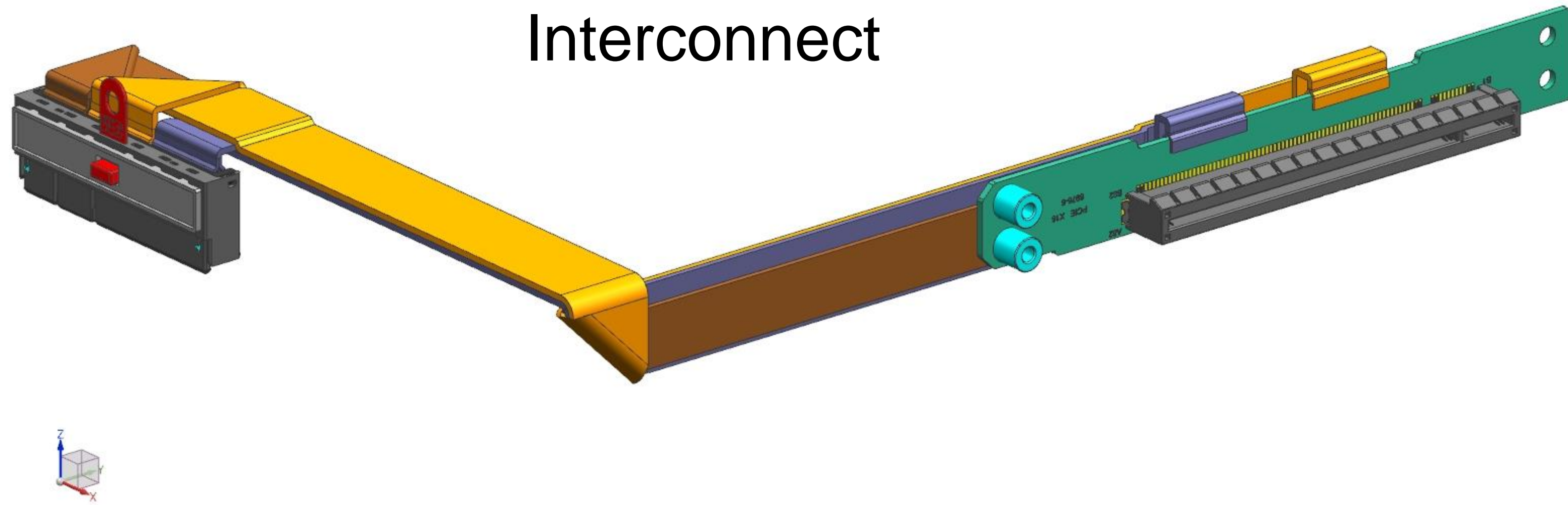


DC-SCM + CPU/Mem/IO



AIC Attachment

IO Slot to CPU Board Cable Harness



AIC Attachment

IO Slot to CPU Board Cable Harness



Gen-Z 4C Connector for attachment to
CPU/Memory Module

SFF-TA-1002 4C Scalable Connector

PCIe Slot Connector for
an Add-in Card in
PCIe CEM form factor

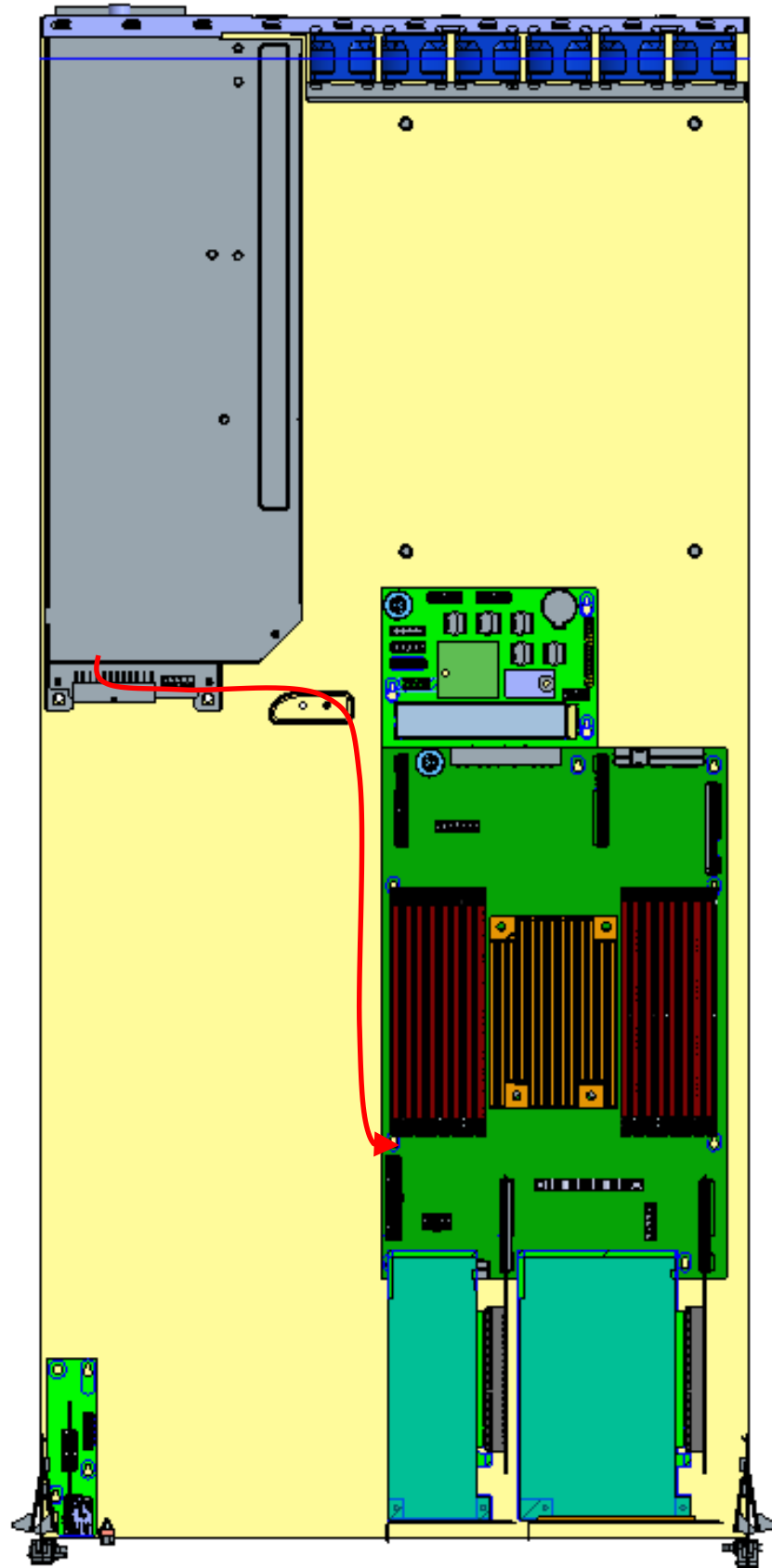
PCIe Slot to Gen-Z Pin Map

ASSEMBLY PINOUT TABLE			ASSEMBLY PINOUT TABLE		
PCIe Side-A		Gen-Z Side-A	PCIe Side-B		Gen-Z Side-B
P1	Description	P2	P1	Description	P2
A1	PRSNT_1	A1	B1, B2, B3	P12V	B1/B2/B3/B4/B5/B6
A2, A3	P12V	A5	B4	GND	GND
A4	GND	A5	B5	SMCLK	A7
A5	JTAG2	A42	B6	SMDAT	A8
A6	JTAG3	A2	B7	GND	B13
A7	JTAG4	A3	B8	P3.3V	A69/B68/B69
A8	JTAG5	A4	B9	JTAG1	A68
A9, A10	P3.3V	A69/B68/B69	B10	P3.3V_AUX	B11
A11	PWRGD	B10	B11	WAKE	A70
A12	GND	A6	B12	CLKREQ	A11
A13	REFCLK_P	B15	B13	GND	B16
A14	REFCLK_N	B14	B14	HS0N_0 (TX)	B17
A15	GND	A13	B15	HS0P_0(TX)	B18
A16	HSIN_0 (RX)	A17	B16	GND	GND
A17	HSIP_0 (RX)	A18	B17	NC_PRSNT_2_B17	NC
A18	GND	A16	B18	GND	B19
A19	NC_RSVD_1	NC	B19	HS0N_1(TX)	B20
A20	GND	A19	B20	HS0P_1(TX)	B21
A21	HSIN_1(RX)	A20	B21, B22	GND	B22
A22	HSIP_1(RX)	A21	B23	HS0N_2(TX)	B23
A23, A24	GND	A22	B24	HS0P_2(TX)	B24
A25	HSIN_2(RX)	A23	B25, B26	GND	B25
A26	HSIP_2(RX)	A24	B27	HS0N_3(TX)	B26
A27, A28	GND	A25	B28	HS0P_3(TX)	B27
A29	HSIN_3(RX)	A26	B29	GND	B28
A30	HSIP_3(RX)	A27	B30	PWRBRK	B8
A31	GND	A28	B31	PRSNT_2_B31	A12
A32	NC_RSVD_2	NC	B32	GND	B29
A33	NC_RSVD_3	NC	B33	HS0N_4(TX)	B30
A34	GND	A29	B34	HS0P_4(TX)	B31
A35	HSIN_4(RX)	A30	B35, B36	GND	B32
A36	HSIP_4(RX)	A31	B37	HS0N_5(TX)	B33
A37, A38	GND	A32	B38	HS0P_5(TX)	B34
A39	HSIN_5(RX)	A33	B39, B40	GND	B35
A40	HSIP_5(RX)	A34	B41	HS0N_6(TX)	B36
A41, A42	GND	A35	B42	HS0P_6(TX)	B37
A43	HSIN_6(RX)	A36	B43, B44	GND	B38
A44	HSIP_6(RX)	A37	B45	HS0N_7(TX)	B39
A45, A46	GND	A38	B46	HS0P_7(TX)	B40
A47	HSIN_7(RX)	A39	B47	GND	B41
A48	HSIP_7(RX)	A40	B48	PRSNT_2_B48	B42
A49	GND	A41	B49	GND	B43
A50	NC_RSVD_5	NC	B50	HS0N_8(TX)	B44
A51	GND	A43	B51	HS0P_8(TX)	B45
A52	HSIN_8(RX)	A44	B52, B53	GND	B46
A53	HSIP_8(RX)	A45	B54	HS0N_9(TX)	B47
A54, A55	GND	A46	B55	HS0P_9(TX)	B48
A56	HSIN_9(RX)	A47	B56, B57	GND	B49
A57	HSIP_9(RX)	A48	B58	HS0N_10(TX)	B50
A58, A59	GND	A49	B59	HS0P_10(TX)	B51
A60	HSIN_10(RX)	A50	B60, B61	GND	B52
A61	HSIP_10(RX)	A51	B62	HS0N_11(TX)	B53
A62, A63	GND	A52	B63	HS0P_11(TX)	B54
A64	HSIN_11(RX)	A53	B64, B65	GND	B55
A65	HSIP_11(RX)	A54	B66	HS0N_12(TX)	B56
A66, A67	GND	A55	B67	HS0P_12(TX)	B57
A68	HSIN_12(RX)	A56	B68, B69	GND	B58
A69	HSIP_12(RX)	A57	B70	HS0N_13(TX)	B59
A70, A71	GND	A58	B71	HS0P_13(TX)	B60
A72	HSIN_13(RX)	A59	B72, B73	GND	B61
A73	HSIP_13(RX)	A60	B74	HS0N_14(TX)	B62
A74, A75	GND	A61	B75	HS0P_14(TX)	B63
A76	HSIN_14(RX)	A62	B76, B77	GND	B64
A77	HSIP_14(RX)	A63	B78	HS0N_15(TX)	B65
A78, A79	GND	A64	B79	HS0P_15(TX)	B66
A80	HSIN_15(RX)	A65	B80	GND	B67
A81	HSIP_15(RX)	A66	B81	PRSNT_2_B81	B70
A82	GND	A67	B82	GND	GND
NC	NC_MGMT_RST	A9	NC	NC_MFG	B7
NC	NC_LED/ACTIVITY	A10	NC	NC_DUALPORTEN	B9
NC	NC_REFCLK1_P	A14	NC	NC_PWRDIS	B12
NC	NC_REFCLK1_N	A15			

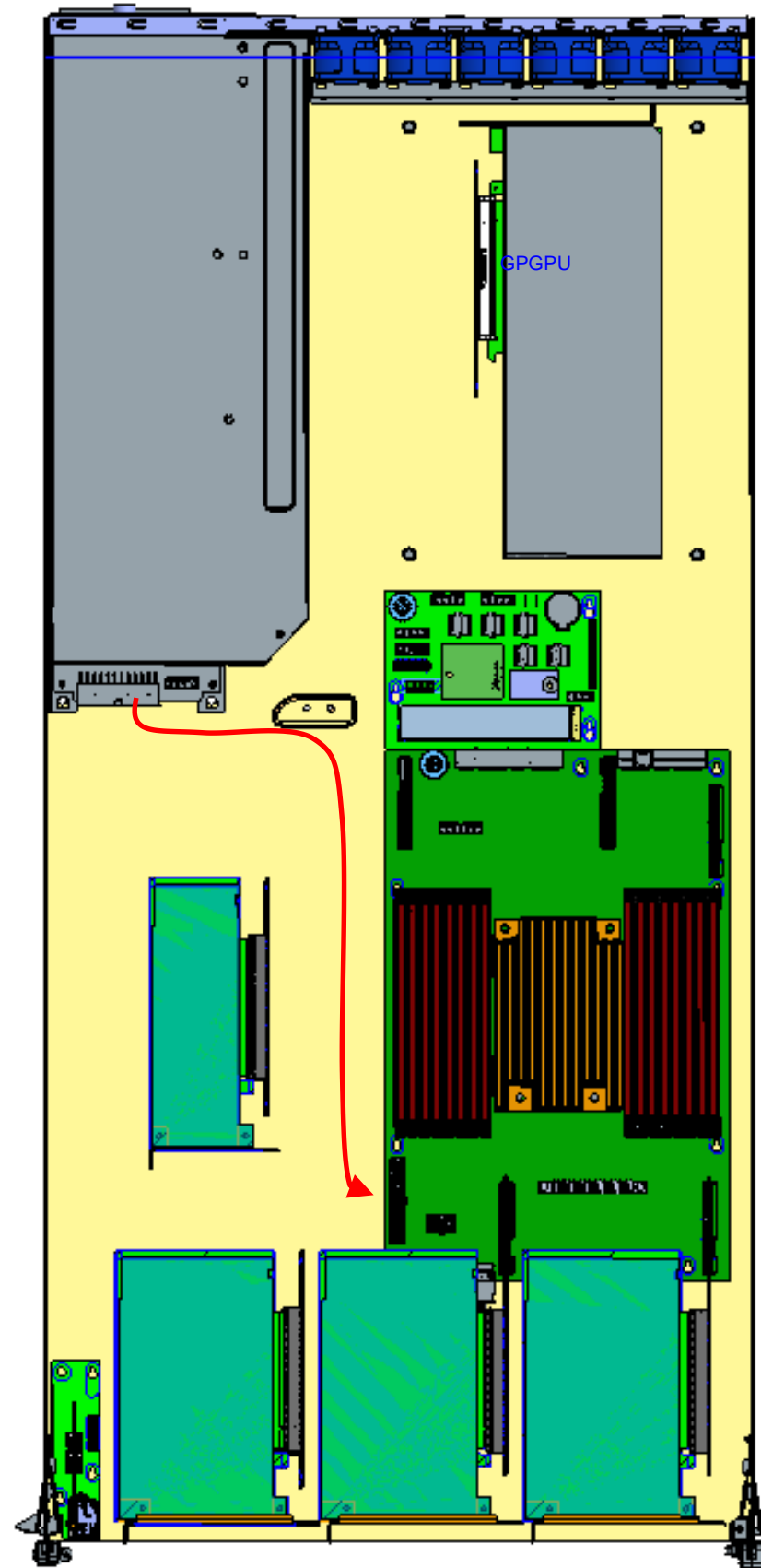
Ground pin	Zero volt reference, all tied together
Power pin	Supplies power to the card
High speed pin	High speed signals
Detect	Sense Pin
Other aux	May be pulled low or sensed by multiple cards
Reserved	Reserved for future use and no connect

Examples of Modular Designs

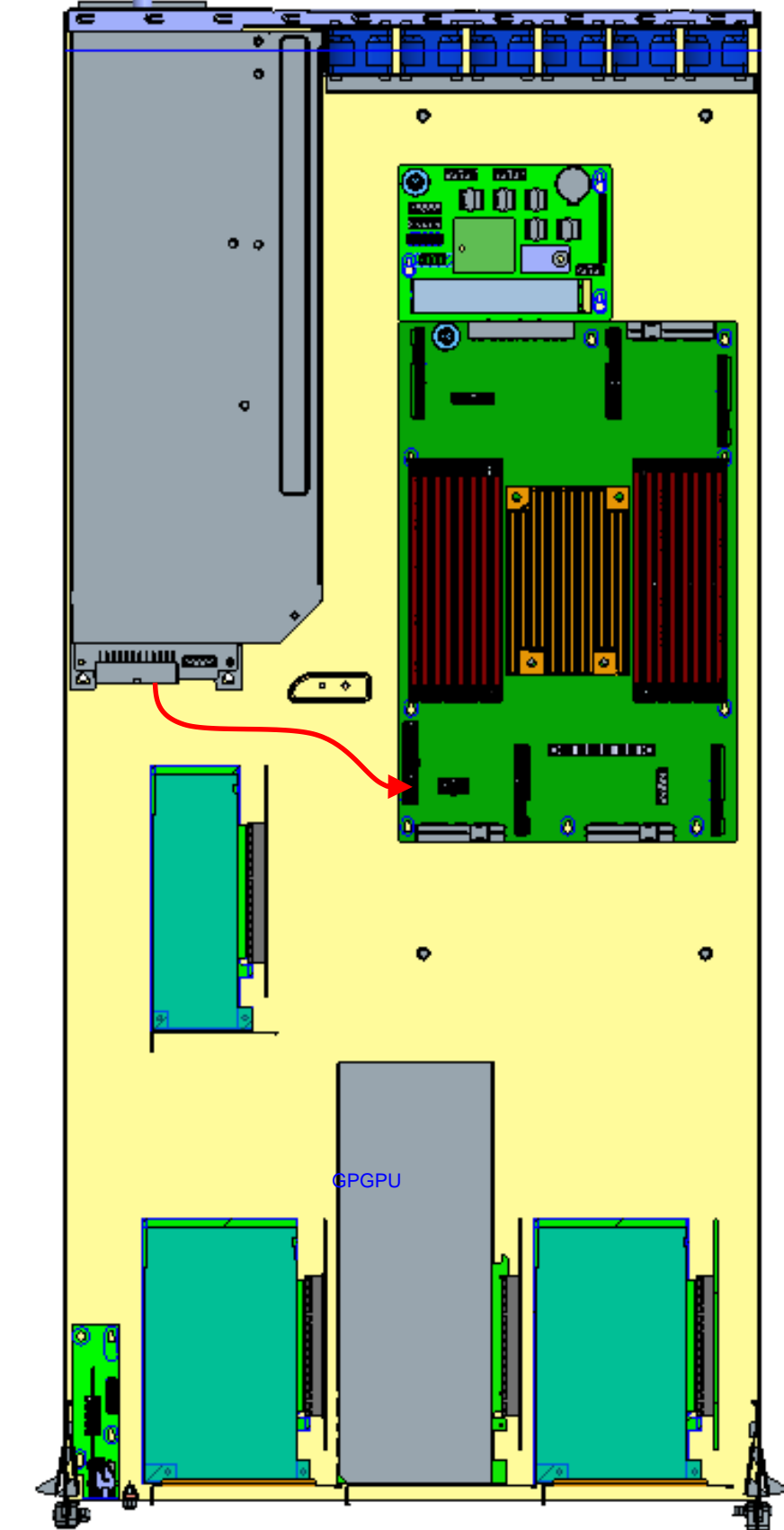
Two Riser Boards & Two AICs



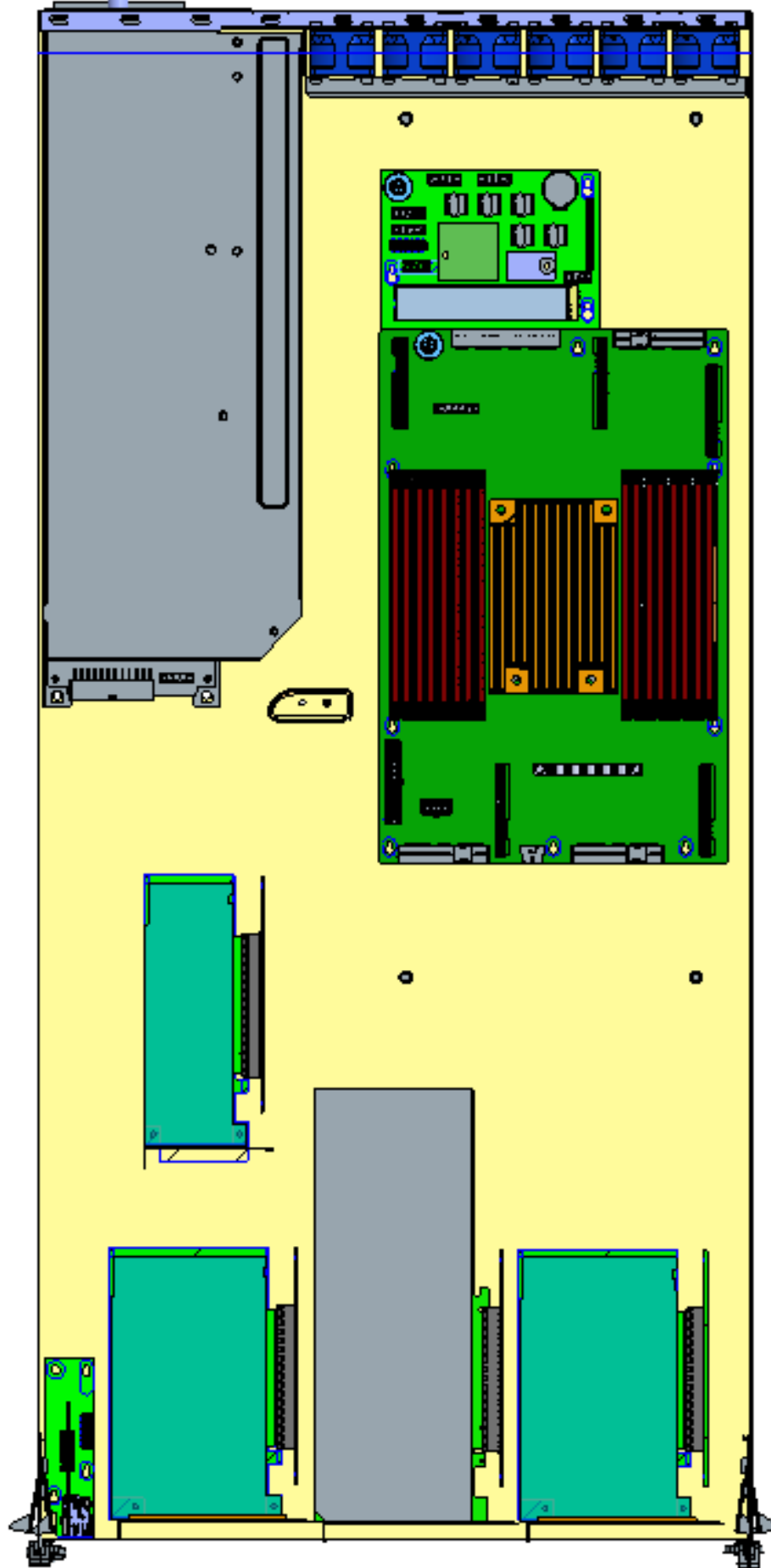
Six AICs (Two Risers, Four Cables)



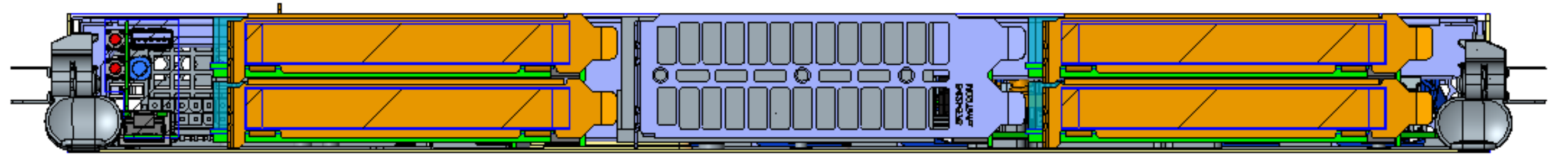
Eight AICs with Cables (or DW AICs)



Two IO Slots in 1U Height



Front View:



The Datacenter-Ready Secure Control Module (***DC-SCM***)

&

The Datacenter-Ready Secure Control Interface (***DC-SCI***)

DC-SCM displaces the Motherboard

Do it once, step, and repeat

Intercept Innovative Work

DC-SCM (in a nutshell)

- DC-SCM is “the heart of the motherboard” when we extract CPU(PCH)/Memory and IO Slots
- Given a traditional 1S, 2S, 4S, ... Motherboard, extract CPU/PCH, DIMM Slots, IO Slots, and the associated VRs, Clock Drivers, and Reset Circuitry, and move them to a new Module
- The residual is the DC-SCM which will include everything else such as BMC, RoT, Flash, Boot SSD, connectors for Fan control, and PSU control

DC-SCM

- Reduce the problem to that which has been solved before
- “***Same as before***” with F/W, S/W, and Services:
 - maintaining the established tools and solutions experience
 - Same management, power sequencing, reset, FRU ID, VPD, ...

•

DC-SCM

- Reduce the problem to that which has been solved before
- “*Same as before*” with F/W, S/W, and Services:
 - maintaining the established tools and solutions experience
 - Same management, power sequencing, reset, FRU ID, VPD, ...
- A vehicle to drive a common Boot, Monitoring, Control, and Remote Debug procedures for
 - Xeon, EPYC, ARM64, Power Servers
 - firmware, diagnostic tools, manufacturing tools

Software Standardization

- Collaborating with CPU suppliers, Open Computing Project community (**OCP**), and Open Software Foundation (**OSF**) to standardize the hardware and software interfaces for the industry **OpenBMC** with **RedFish** transport and for the system BIOS/UEFI based on **EDK-II**

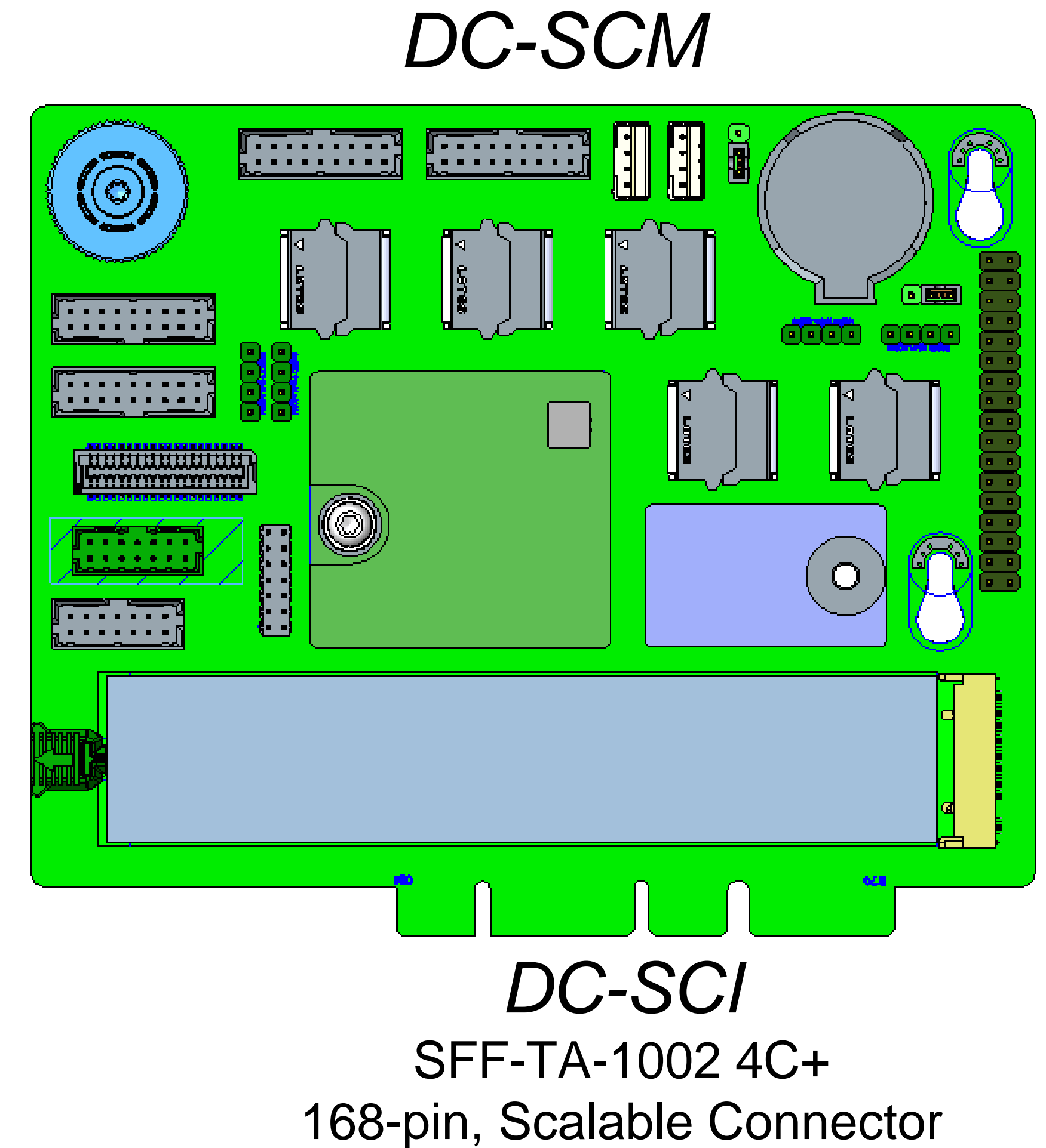
Collaboration and Feedback

- To ensure we have all aspects covered for upcoming servers
- We sought feedback from our industry colleagues encouraging them to provide part- and pin-list for DC-SCM
- We have compiled the feedback and proposals into a useful specification for various server types and expansion chassis so that they may be datacenter-ready

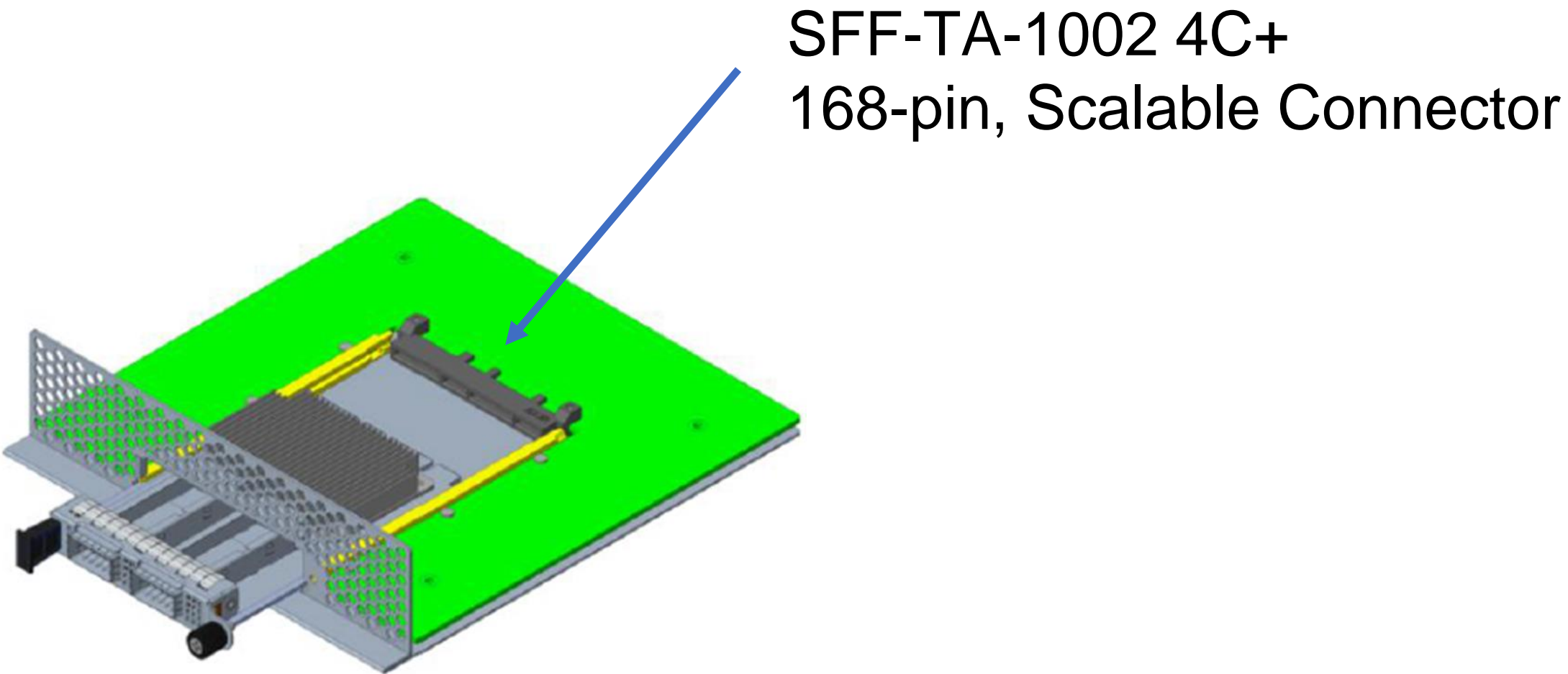
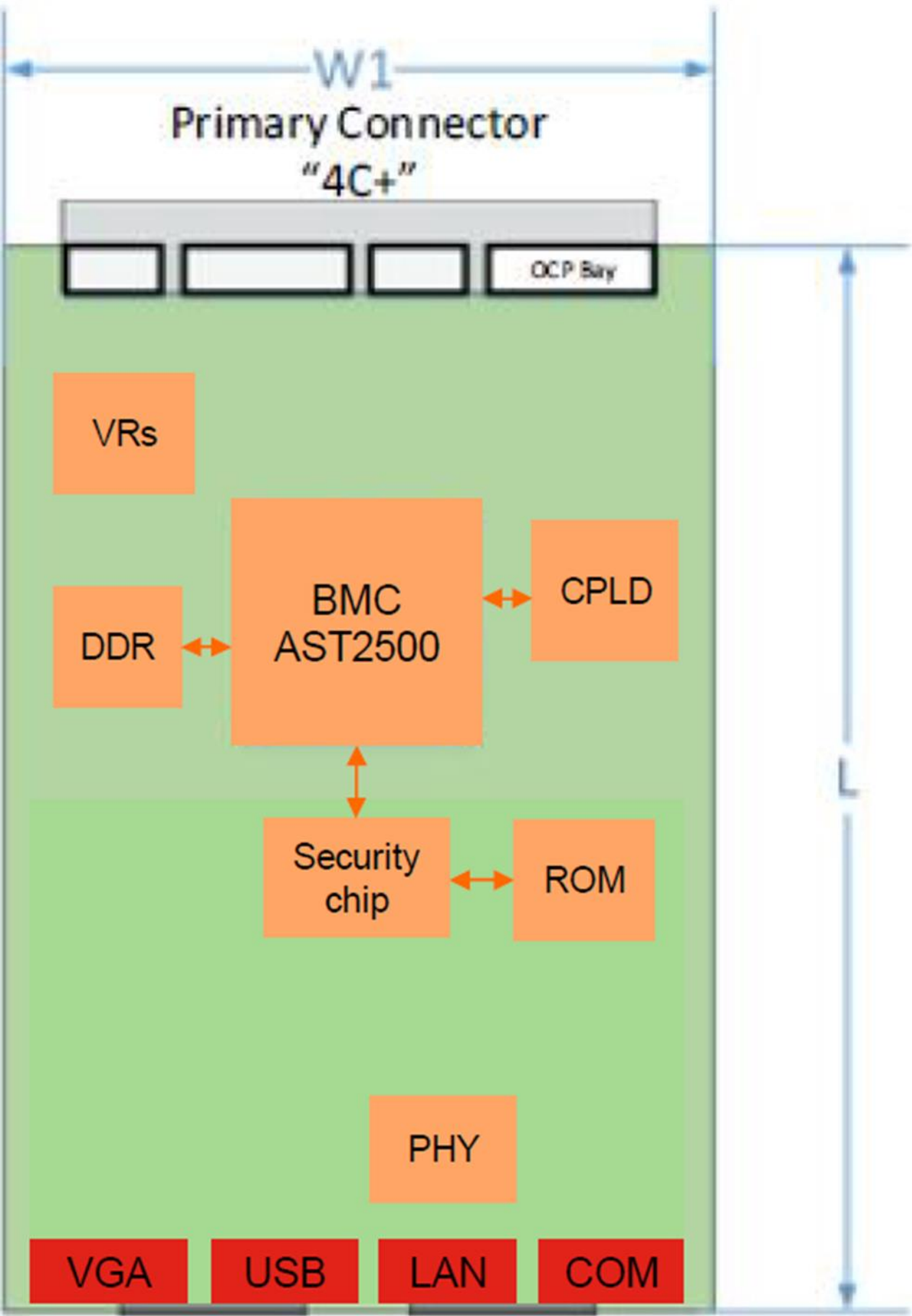
An example of DC-SCM

DC-SCM

- Receives Power
- Remote Control at Cloud Scale
 - CPU/Memory/IO Module (Xeon, EPYC, ARM64)
 - Expansion Chassis (JBOD, JBOG)
 - Fans, PSUs
- Includes
 - BMC and Rack Management Interface
 - Flash Devices (all FW)
 - RoT and TPM for Security
 - Optional Boot SSD
 - Remote, at-scale Debug



Another Example of DC-SCM (OCP NIC3 Form Factor)



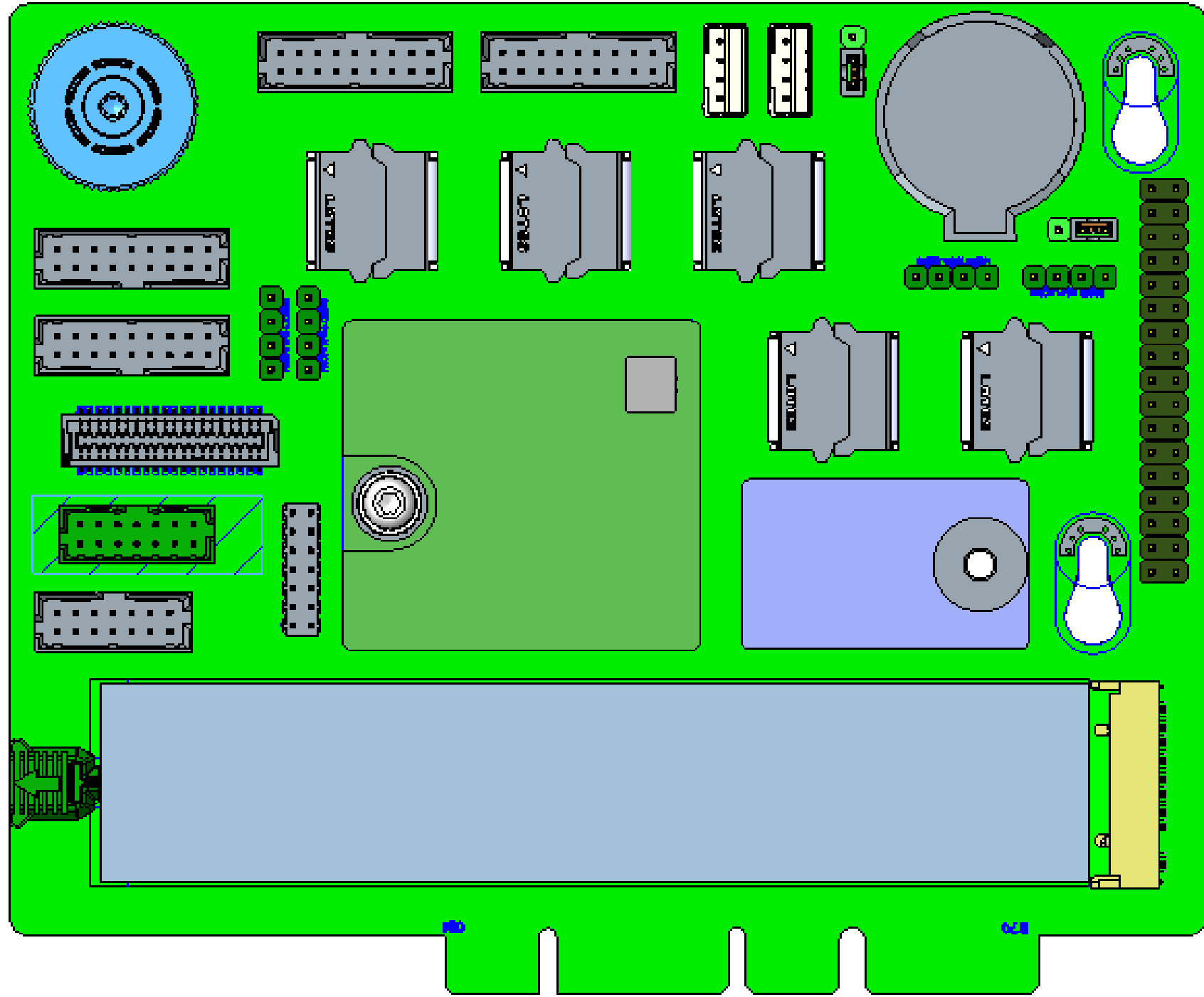
Form Factor	Width	Depth	Primary Connector	Secondary Connector
SFF	W1 = 76 mm	L = 115 mm	"4C+" 168 pins	N/A

DC-SCM

- The secure control module (SCM) includes all other system related components normally present on Motherboards
- Baseboard Management Controller (BMC), Realtime Clock (RTC), FAN/PSU Control, Root of Trust Chip (RoT: Cerberus and the associated circuitry), BIOS & BMC Flash, and the Boot Device
- The SCM is small enough to fit anywhere in the Chassis (not necessarily at the front, coplanar, vertical attached, cabled)
- Most building blocks are stateless
- SCM holds control bits secured

An Example of SCM Expander Connectors

Item	Function	Qty
1	M2 socket	1
2	TPM connector	1
3	SPI socket	5
4	RoT connector	1
5	VGA cable connector	1
6	NCSI cable connector	1
7	Front panel cable connector	1
8	FAN cable connector	2
9	BMC debug UART Pin header	1
10	HOST UART Pin header	1
11	Auxiliary UART Pin header	1
12	Reserved UART Pin header	1
13	Pin header	2
14	PSU cable connector	2
15	JATG cable connector	1
16	Reserved USB cable header	1
17	ID LED header	1
18	Battery	1
19	I2C Header	1
23	Golden Finger	1

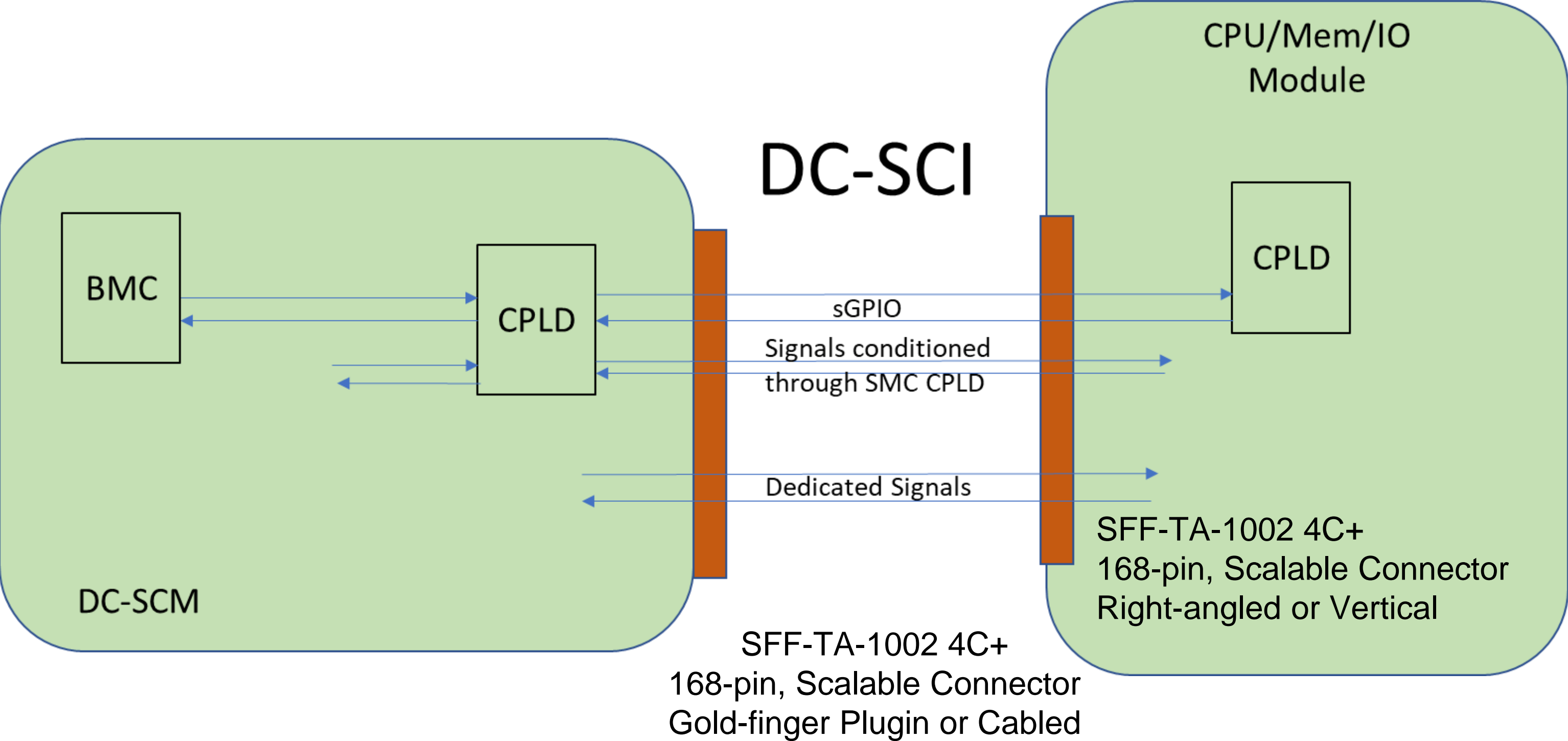


SFF-TA-1002 4C+
168-pin, Scalable Connector

DC-SCM to CPU/Mem Module Interface (DC-SCI)

Pinout and definition

Pin Reduction via SGPIO



I2C with Alert#	36	ADR_Complete	1
PECI	2	ModulePowerEn	1
JTAG	5	ModulePowerOK	1
Remote Debug	6	SysHardReset_N	1
LPC/eSPI	12	WarmReset_N	1
SPI	6	IO_Reset_N	1
SPI (Second Port)	4	Expander Reset_L	1
TPM	2	SYS_PWRBTN_N	1
USB	2	RSTBTN_OUT_N	1
UART	2	ME Recovery	1
PCIe Clock	2	SLP_A	1
BMC PCIe	5	GPIO Reset_L	1
M.2 PCIe	18	SGPIO 1	4
USB 2.0	2	SGPIO 2	4
BMC_NMI_N	1	Power	5
SMI_Active_N	1	GND/Return	26
CPU CatErr_N	1	Reserved	8
Inter-BMC_CPU	2	Total	168

DC-SCI (pinout proposal)

Connector Type:
SFF-TA-1002 4C+
168-pin, Scalable Connector

DC-SCM Connector:
Gold-finger

CPU/Memory/IO Module Connector:
Right-angled or Vertical Recepticle

I2C with Alert#	36	ADR_Complete	1
PECI	2	ModulePowerEn	1
JTAG	5	ModulePowerOK	1
Remote Debug	6	SysHardReset_N	1
LPC/eSPI	12	WarmReset_N	1
SPI	6	IO_Reset_N	1
SPI (Second Port)	4	Expander Reset_L	1
TPM	2	SYS_PWRBTN_N	1
USB	2	RSTBTN_OUT_N	1
UART	2	ME Recovery	1
PCIe Clock	2	SLP_A	1
BMC PCIe	5	GPIO Reset_L	1
M.2 PCIe	18	SGPIO 1	4
USB 2.0	2	SGPIO 2	4
BMC_NMI_N	1	Power	5
SMI_Active_N	1	GND/Return	26
CPU CatErr_N	1	Reserved	8
Inter-BMC_CPU	2	Total	168

Win-win

DC-SCM accelerates deploying servers from various suppliers into the datacenter

Standardizing DC-SCI for ease of integration into various datacenters

- From a Datacenter point of view:
with one DC-SCM, a datacenter may support multiple variants of servers (AMD-, Xeon-, ARM64-based 1S, 2S, 4S, ...) and expansion chassis, JBODs, JBOG, JBOFs, ...
- From OEM/ODMs' point of view:
A product will fit datacenters of various CSPs or Hyperscalers

If we are smart, one DC-SCM may enable supplier products into different DC types; otherwise, each Datacenter Provider may have its own version of DC-SCM

Call to Action

Design your Servers, Expansion Chassis, JBODs, JBODGs, JBODFs, etc. with DC-SCI connector in mind.

Make your solution Datacenter-Ready!

Visit Microsoft Booth for an example of DC-SCM and MBA

Join the effort to enhance DC-SCM and DC-SCI

<https://www.opencompute.org/projects/server>



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Q&A

Presenter

[Siamak Tavallaei](#) is a Principal Architect at Microsoft Azure and co-chair of OCP Server Project. Collaborating with industry partners, he drives several initiatives in research, design, and deployment of hardware for Microsoft's cloud-scale services at Azure. He is interested in Big Compute, Big Data, and Artificial Intelligence solutions based on distributed, heterogeneous, accelerated, and energy-efficient computing. His current focus is the optimization of large-scale, mega-datacenters for general-purpose computing and accelerated, tightly-connected, problem-solving machines built on collaborative designs of hardware, software, and management.



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